

# DATA SHEET

## **PDTC143Z series**

**NPN resistor-equipped transistors;**

**R1 = 4.7 k $\Omega$ , R2 = 47 k $\Omega$**

Product data sheet  
Supersedes data of 2004 Apr 06

2004 Aug 16

## NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 47 k $\Omega$

## PDTC143Z series

### FEATURES

- Built-in bias resistors
- Simplified circuit design
- Reduction of component count
- Reduced pick and place costs.

### APPLICATIONS

- General purpose switching and amplification
- Inverter and interface circuits
- Circuit driver.

### QUICK REFERENCE DATA

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	–	50	V
I <sub>O</sub>	output current (DC)	–	100	mA
R1	bias resistor	4.7	–	k $\Omega$
R2	bias resistor	47	–	k $\Omega$

### DESCRIPTION

NPN resistor-equipped transistor (see “Simplified outline, symbol and pinning” for package details).

### PRODUCT OVERVIEW

TYPE NUMBER	PACKAGE		MARKING CODE	PNP COMPLEMENT
	PHILIPS	EIAJ		
PDTC143ZE	SOT416	SC-75	38	PDTA143ZE
PDTC143ZEF	SOT490	SC-89	53	PDTA143ZEF
PDTC143ZK	SOT346	SC-59	18	PDTA143ZK
PDTC143ZM	SOT883	SC-101	E3	PDTA143ZM
PDTC143ZS	SOT54 (TO-92)	SC-43	TC143Z	PDTA143ZS
PDTC143ZT	SOT23	–	*18 <sup>(1)</sup>	PDTA143ZT
PDTC143ZU	SOT323	SC-70	*54 <sup>(1)</sup>	PDTA143ZU

### Note

- \* = p: Made in Hong Kong.  
\* = t: Made in Malaysia.  
\* = W: Made in China.

NPN resistor-equipped transistors;  
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PDTC143Z series

SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL	PINNING	
		PIN	DESCRIPTION
PDTC143ZS		1 2 3	base collector emitter
PDTC143ZE PDTC143ZEF PDTC143ZK PDTC143ZT PDTC143ZU		1 2 3	base emitter collector
PDTC143ZM		1 2 3	base emitter collector

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PDTC143Z series

## ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PDTC143ZE	–	plastic surface mounted package; 3 leads	SOT416
PDTC143ZEF	–	plastic surface mounted package; 3 leads	SOT490
PDTC143ZK	–	plastic surface mounted package; 3 leads	SOT346
PDTC143ZM	–	leadless ultra small plastic package; 3 solder lands; body 1.0 × 0.6 × 0.5 mm	SOT883
PDTC143ZS	–	plastic single-ended leaded (through hole) package; 3 leads	SOT54
PDTC143ZT	–	plastic surface mounted package; 3 leads	SOT23
PDTC143ZU	–	plastic surface mounted package; 3 leads	SOT323

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CB0</sub>	collector-base voltage	open emitter	–	50	V
V <sub>CEO</sub>	collector-emitter voltage	open base	–	50	V
V <sub>EBO</sub>	emitter-base voltage	open collector	–	10	V
V <sub>I</sub>	input voltage				
	positive		–	+30	V
	negative		–	–5	V
I <sub>O</sub>	output current (DC)		–	100	mA
I <sub>CM</sub>	peak collector current		–	100	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C			
	SOT54	note 1	–	500	mW
	SOT23	note 1	–	250	mW
	SOT346	note 1	–	250	mW
	SOT323	note 1	–	200	mW
	SOT883	notes 2 and 3	–	250	mW
	SOT416	note 1	–	150	mW
SOT490	notes 1 and 2	–	250	mW	
T <sub>stg</sub>	storage temperature		–65	+150	°C
T <sub>j</sub>	junction temperature		–	150	°C
T <sub>amb</sub>	operating ambient temperature		–65	+150	°C

## Notes

1. Refer to standard mounting conditions.
2. Reflow soldering is the only recommended soldering method.
3. Refer to SOT883 standard mounting conditions; FR4 with 60  $\mu$ m copper strip line.

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PDTC143Z series

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air		
	SOT54	note 1	250	K/W
	SOT23	note 1	500	K/W
	SOT346	note 1	500	K/W
	SOT323	note 1	625	K/W
	SOT883	notes 2 and 3	500	K/W
	SOT416	note 1	833	K/W
SOT490	notes 1 and 2	500	K/W	

### Notes

1. Refer to standard mounting conditions.
2. Reflow soldering is the only recommended soldering method.
3. Refer to SOT883 standard mounting conditions; FR4 with 60  $\mu\text{m}$  copper strip line.

### CHARACTERISTICS

T<sub>amb</sub> = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = 50 V; I <sub>E</sub> = 0 A	–	–	100	nA
I <sub>CEO</sub>	collector-emitter cut-off current	V <sub>CE</sub> = 30 V; I <sub>B</sub> = 0 A	–	–	1	$\mu\text{A}$
		V <sub>CE</sub> = 30 V; I <sub>B</sub> = 0 A; T <sub>j</sub> = 150 °C	–	–	50	$\mu\text{A}$
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = 5 V; I <sub>C</sub> = 0 A	–	–	170	$\mu\text{A}$
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 5 V; I <sub>C</sub> = 10 mA	100	–	–	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = 5 mA; I <sub>B</sub> = 0.25 mA	–	–	100	mV
V <sub>i(off)</sub>	input-off voltage	I <sub>C</sub> = 100 $\mu\text{A}$ ; V <sub>CE</sub> = 5 V	–	0.6	0.5	V
V <sub>i(on)</sub>	input-on voltage	I <sub>C</sub> = 5 mA; V <sub>CE</sub> = 0.3 V	1.3	0.9	–	V
R1	input resistor		3.3	4.7	6.1	k $\Omega$
$\frac{R2}{R1}$	resistor ratio		8	10	12	
C <sub>c</sub>	collector capacitance	I <sub>E</sub> = i <sub>e</sub> = 0 A; V <sub>CB</sub> = 10 V; f = 1 MHz	–	–	2.5	pF

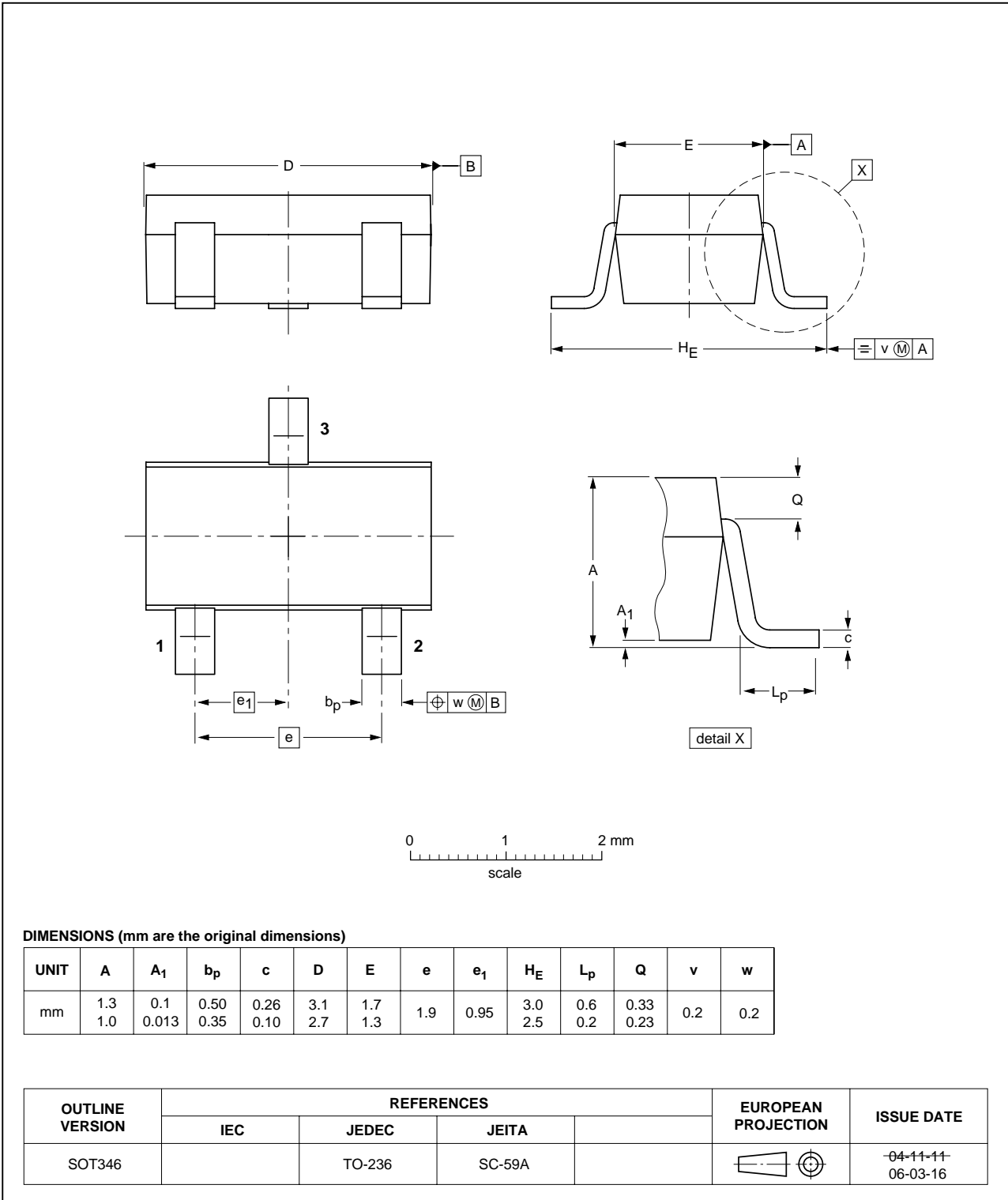
NPN resistor-equipped transistors;  
R1 = 4.7 kΩ, R2 = 47 kΩ

PDTC143Z series

PACKAGE OUTLINES

Plastic surface-mounted package; 3 leads

SOT346

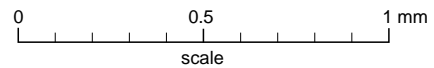
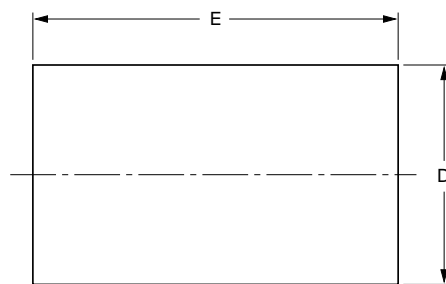
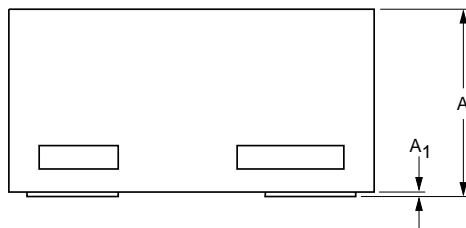
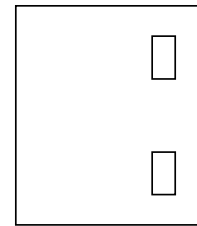
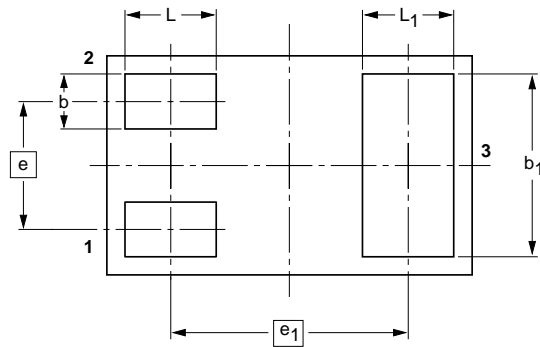


NPN resistor-equipped transistors;  
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PDTC143Z series

Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm

SOT883



**DIMENSIONS (mm are the original dimensions)**

UNIT	A <sup>(1)</sup>	A <sub>1</sub> max.	b	b <sub>1</sub>	D	E	e	e <sub>1</sub>	L	L <sub>1</sub>
mm	0.50 0.46	0.03	0.20 0.12	0.55 0.47	0.62 0.55	1.02 0.95	0.35	0.65	0.30 0.22	0.30 0.22

**Note**

1. Including plating thickness

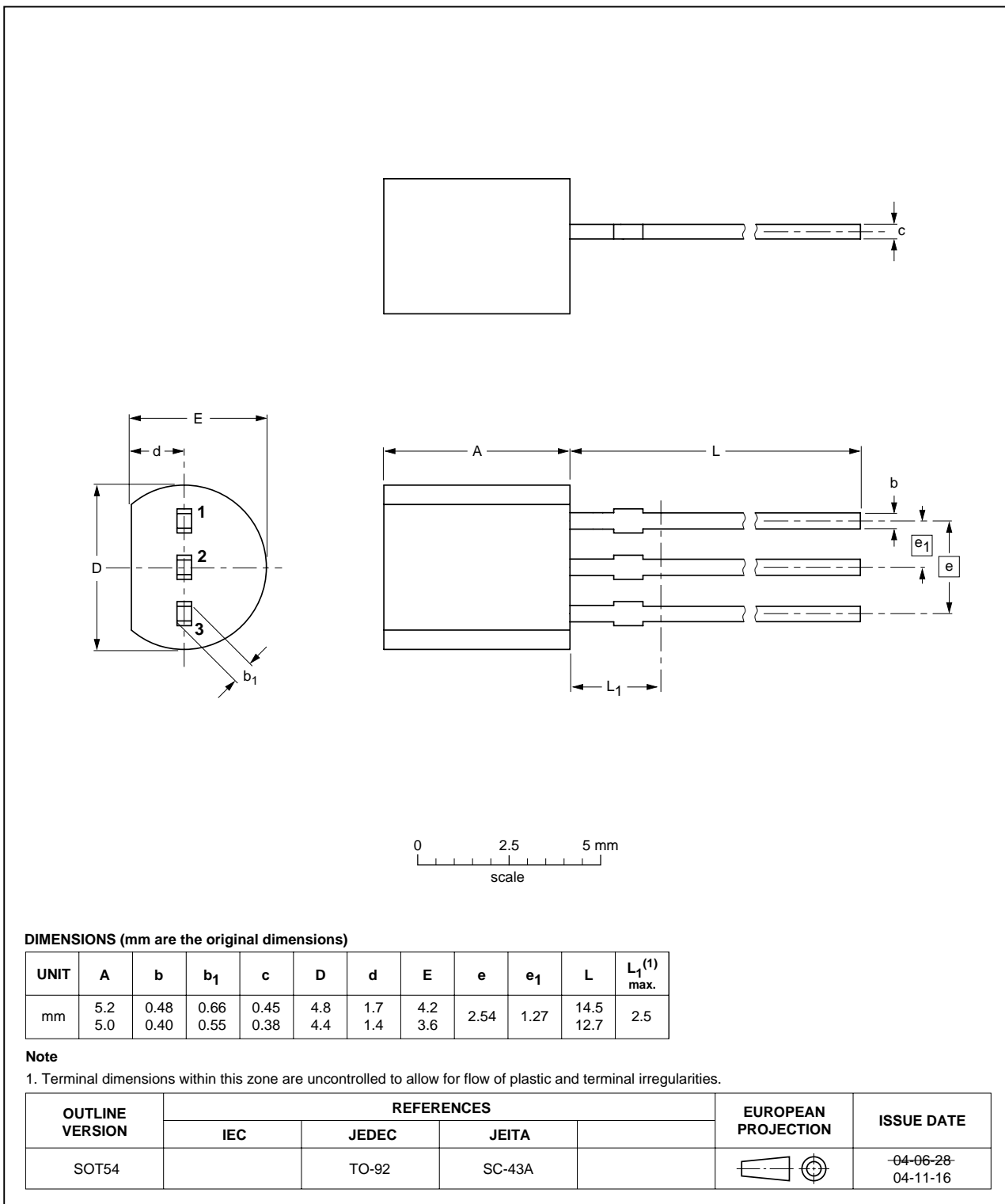
OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT883			SC-101		03-02-05 03-04-03

NPN resistor-equipped transistors;  
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PDTC143Z series

Plastic single-ended leaded (through hole) package; 3 leads

SOT54



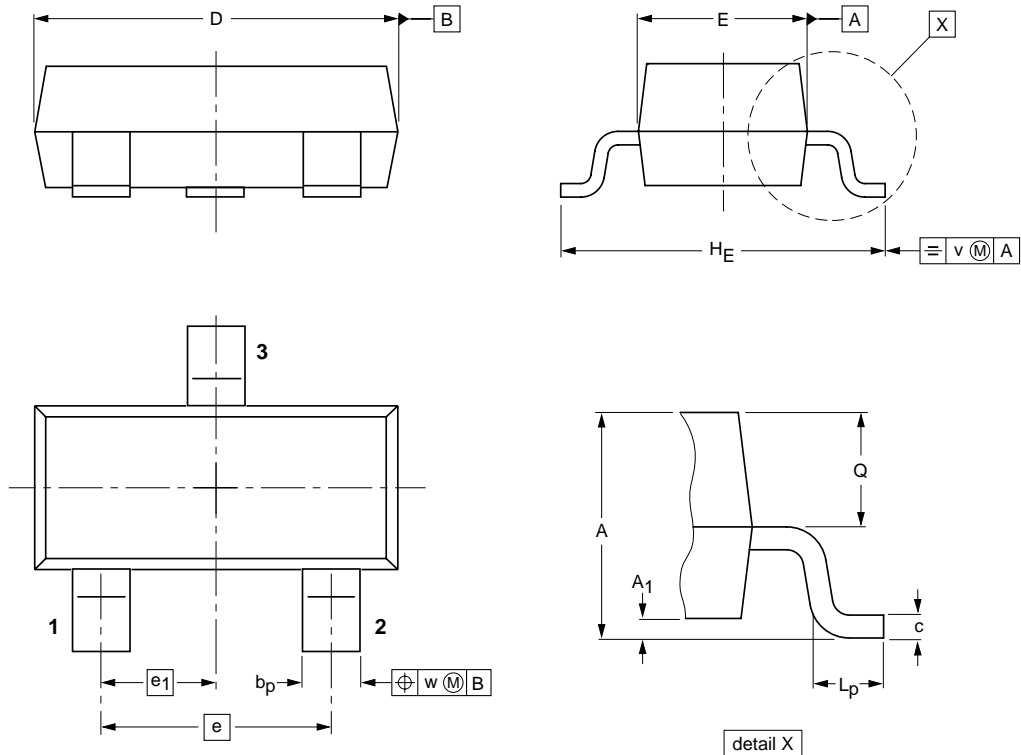


NPN resistor-equipped transistors;  
R1 = 4.7 kΩ, R2 = 47 kΩ

PDTC143Z series

Plastic surface-mounted package; 3 leads

SOT23



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max.	b <sub>p</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

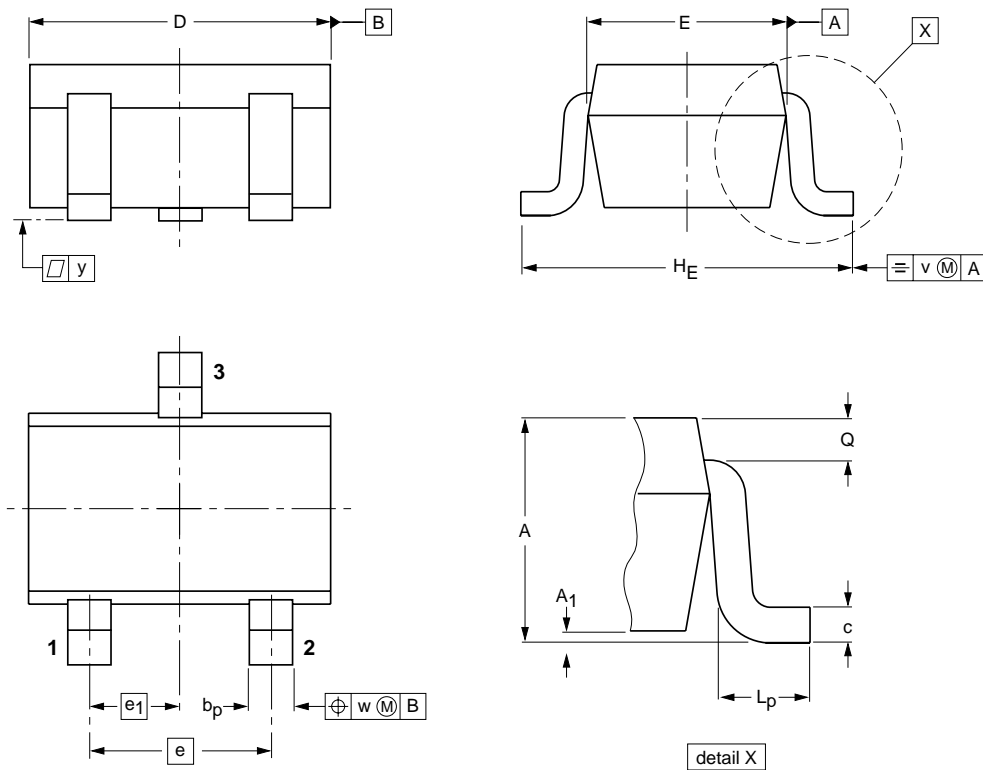
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	IEC	JEDEC	JEITA		
SOT23		TO-236AB			04-11-04 06-03-16

NPN resistor-equipped transistors;  
R1 = 4.7 kΩ, R2 = 47 kΩ

PDTC143Z series

Plastic surface-mounted package; 3 leads

SOT323



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	b <sub>p</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

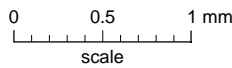
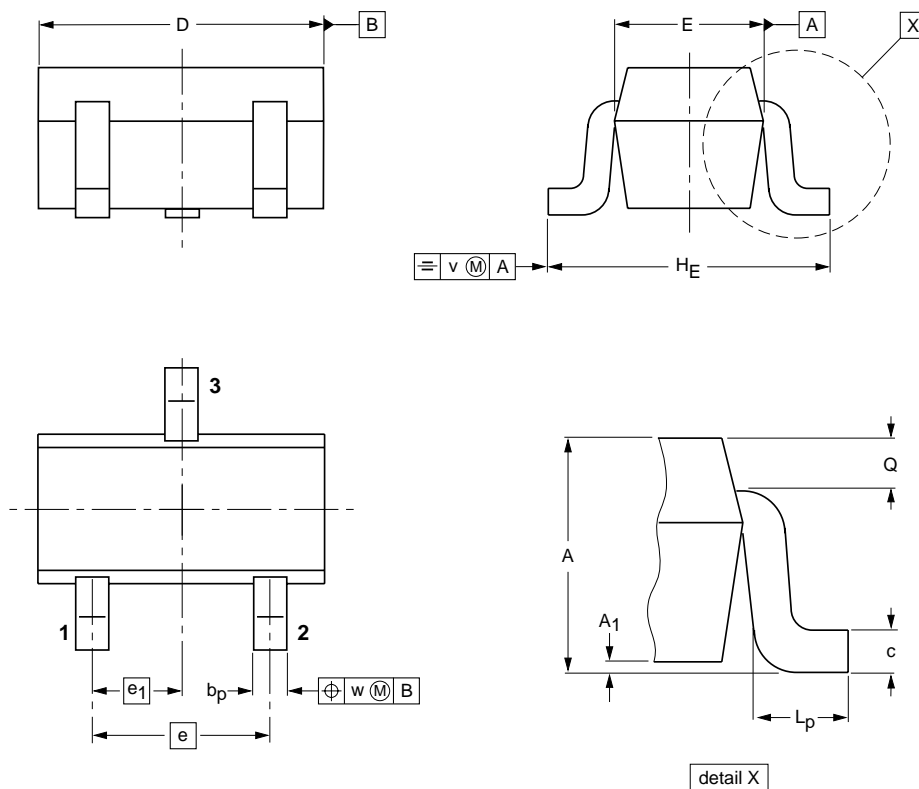
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT323			SC-70			<del>04-11-04</del> 06-03-16

NPN resistor-equipped transistors;  
R1 = 4.7 kΩ, R2 = 47 kΩ

PDTC143Z series

Plastic surface-mounted package; 3 leads

SOT416



**DIMENSIONS** (mm are the original dimensions)

UNIT	A	A1 max	bp	c	D	E	e	e1	HE	Lp	Q	v	w
mm	0.95 0.60	0.1	0.30 0.15	0.25 0.10	1.8 1.4	0.9 0.7	1	0.5	1.75 1.45	0.45 0.15	0.23 0.13	0.2	0.2

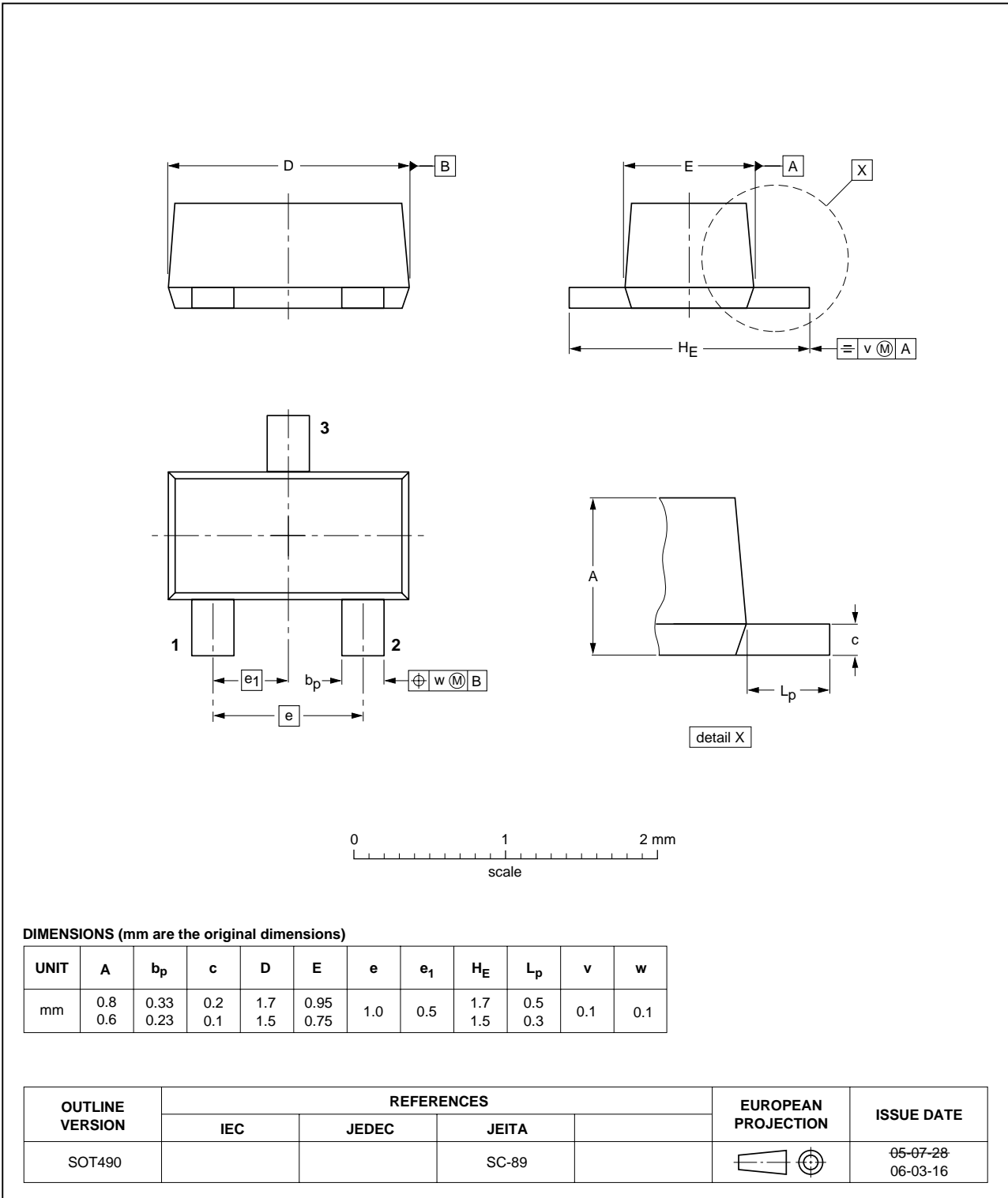
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	IEC	JEDEC	JEITA		
SOT416			SC-75		04-11-04 06-03-16

NPN resistor-equipped transistors;  
R1 = 4.7 kΩ, R2 = 47 kΩ

PDTC143Z series

Plastic surface-mounted package; 3 leads

SOT490



NPN resistor-equipped transistors;  
R1 = 4.7 k $\Omega$ , R2 = 47 k $\Omega$

PDTC143Z series

#### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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1. Please consult the most recently issued document before initiating or completing a design.
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## **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

## **Contact information**

For additional information please visit: <http://www.nxp.com>

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Printed in The Netherlands

R75/07/pp14

Date of release: 2004 Aug 16

Document order number: 9397 750 13677

